

201-1400 Land/Pad Repair Kit

Instruction: INS1067

Page 1 of 2

This kit includes the tools and materials needed to reliably repair or replace damaged lands, surface mount and BGA pads.

The replacement circuits in this kit have a dry film, adhesive backing that is activated and cured with heat. This IPC recommended repair method restores your boards to their original level of performance and reliability.

Includes a temperature-controlled Bonding Iron and Bonding Tips to delivers the optimal heat required for curing the adhesive bonding film on the backside of the replacement lands and pads.

This kit is specifically designed to make the repair process as simple and reliable as possible. All the tools and materials are packaged in a rugged ESD safe carrying case.

See the following instructions pages for more information.



INS1059 Bonding Tips
INS1065 Color Agents
INS1063 Circuit Bond Epoxy
INS1060 Circuit Frames

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Includes the following items.

Qty	Part No. / Item
1	115-3136 Abrader
1	115-2801 Bonding Tip, Tapered
1	115-2803 Bonding Tip, .120" (3.05 mm) Diameter
4	115-3302 Circuit Bond Epoxy
1	CFV003AS Circuit Frame
Pkg/5	235-2102-5 Foam Swab, 3/16" Tip
Pkg/126	235-3025 High Temp Tape Discs
1	355-0614 Knife with #16 Blades
Pkg/5	355-3102-5 Micro Probes
5	115-3312 Plastic Cup
1	335-5188 Tweezer, Crossover

Qty	Part No. / Item
1*	115-3210 Bonding Iron, 120 VAC
1	115-2802 Bonding Tip, .080" (2.03 mm) Diameter
1	115-2805 Bonding Tip, .080" x .120" (2.03 mm x 3.05 mm)
1	CFV002AS Circuit Frame
Pkg/5	235-2106-5 Cleaning Brushes
Pkg/5	235-2108-50 Foam Swab, Large
Pkg/60	235-3050 High Temp Tape Discs
1	115-3115 Measuring Microscope Pen, 25X
Pkg/5	115-3315-5 Mixing Picks
1	335-3195 Probe
1	335-5185 Tweezer, Point Tip

* Model 201-1402 Land/Pad Repair Kit, 230 VAC includes 115-3220 Bonding Iron, 230 VAC